



## SPECIFICATION FOR RoHS 6 COMPLIANT SMT VCTCXO MtronPTI P/N M6056S017

### Electrical Specifications:

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Frequency of Operation	F <sub>o</sub>		16.000000		MHz	
<b>Frequency Stability</b>						
Initial Tolerance	ΔF/F	-1.5		+1.5	ppm	@ +25°C, with V <sub>c</sub> = 1.5V
Frequency Stability	ΔF/F			+0.5	ppm	(F <sub>max</sub> – F <sub>min</sub> )/2, over operating temperature range
Frequency vs. Supply		-0.2		+0.2	ppm	For a ±5% supply voltage change
Frequency vs. Load		-0.2		+0.2	ppm	For a ±10% load change
Aging	F <sub>A</sub>	-1.0		+1.0	ppm	Per year
<b>Output</b>						
Output Type		Clipped Sine Wave				External DC-cut output capacitor (0.001 μF) required.
Output Load		10 kΩ    10 pF				± 10%
Output Levels	V <sub>OUT</sub>	0.8			V <sub>pk-pk</sub>	Load =10K    10 pF
Startup Time	t <sub>SU</sub>			10	ms	
Control Voltage	V <sub>c</sub>	0.5	1.5	2.5	V	
Tuning Range		±5.0			ppm	
<b>Additional Specifications</b>						
SSB Phase Noise (Under Static Conditions)			-85		dBc/Hz	@ 10 Hz Offset
			-110		dBc/Hz	@ 100 Hz Offset
			-135		dBc/Hz	@ 1 kHz Offset
			-150		dBc/Hz	@ 10 kHz Offset
Operating Voltage	V <sub>s</sub>	2.85	3.00	3.15	V <sub>DC</sub>	
Operating Current	I <sub>s</sub>			2.0	mA	

### Environmental & Mechanical Requirements:

Operating Temperature	T <sub>A</sub>	-30		+85	°C	
Storage Temperature	T <sub>S</sub>	-55		+105	°C	
Shock	Per MIL-STD-202, Method 213, Condition C					
Vibration	Per MIL-STD-202, Methods 201 & 204					
Maximum Soldering Conditions	See Figure 1.					
Solderability	See solder profile, Figure 1					
Package Type	3.2 x 2.5 mm, 4-pad Ceramic Leadless Chip Carrier. RoHS Compliant					

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### Dimensions, Pin Out and PAD Layout Information:

Part Marking	
Line 1	16M000
Line 2	M y m vv

Legend	
y	Last digit of year
m	Month letter code
vv	Factory code

Pad	Function
1	Tuning Voltage
2	Ground
3	Output
4	+V <sub>DD</sub>

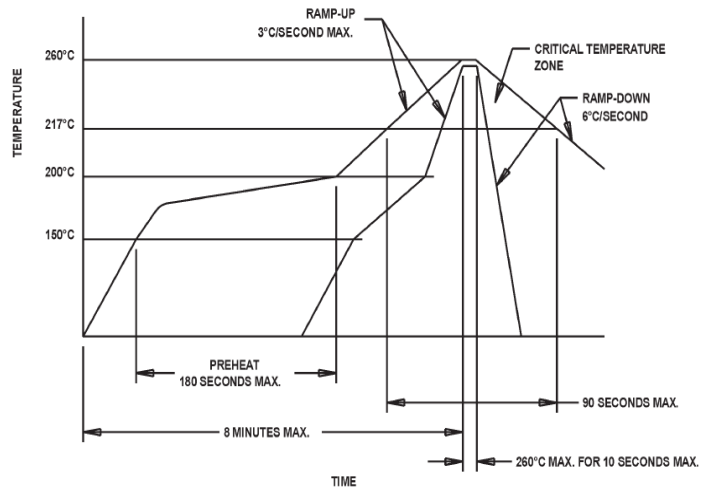
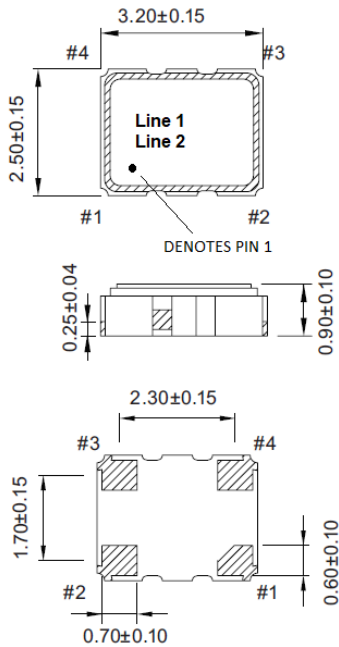
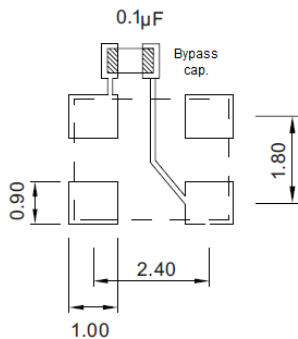


Figure 1

#### SUGGESTED SOLDER PAD LAYOUT



### Data Sheet Revision Table:

Date	Rev.	Author	Details of Revision
05/10/19	0	MM	Original Release.